# **New MicReD Products**

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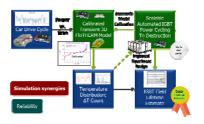
November 2017

### **Notable launches in FY17**

### **PWT 600A 16C**

### Workflow with simulation

- Serves a specific user segment
- Press tour (automotive)
- Mission profile based workflow with simulation



### **DynTIM-S**

### Industrial segmentation

- DynTIM mechanics
- DYnTIM+T3Ster circuits (all MicReD HW)
- For users interested in material properties (priced lower)



### Booster 240A/11V

### Modularity and QA

- Replacing LS200
- Heating at 10..240A, 11V
- 4x gate drive, 1x Is
- PSU's from 3rd party, 4+2U





### **PWT 600A 16C**



- Lighter mechanics (no cold-plate or cavity)
- Measurement: 16 channels (2x2x4)
- Output current: 600A (2x300A)
- Output voltage: 48V
- Power Tester 600A 16C 48V (29kW!)
- Launch date: May 2016

### **PWT 600A 16C features**

- Output current: 2\*300A or 1\*600A / 48V flexible powering
- 2 \* 8 channels MUX
- Gate driver built in with -10 to 20V earth independent Voltage
- No cold plate or water system included
- 2 or more units can be connected and create a system

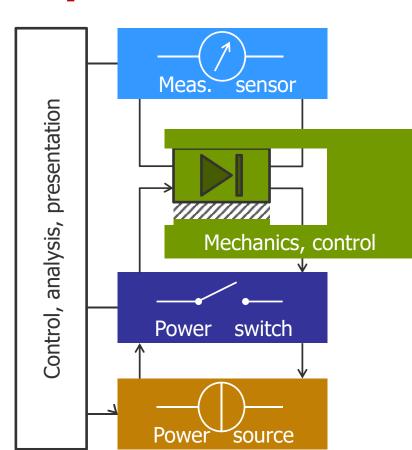
# **DynTIM S - a standalone system**

Measuring bulk thermal conductivity of thermal interface materials by varying thickness

### DynTIM S includes:

- Mechanics for thickness control
- Diode for heating and sensing
- Control electronics
- Heating and sensing circuits

No other MicReD HW is needed





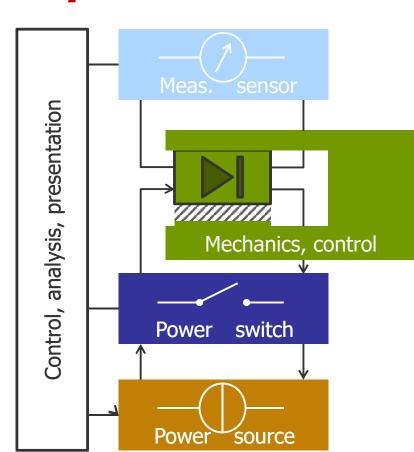
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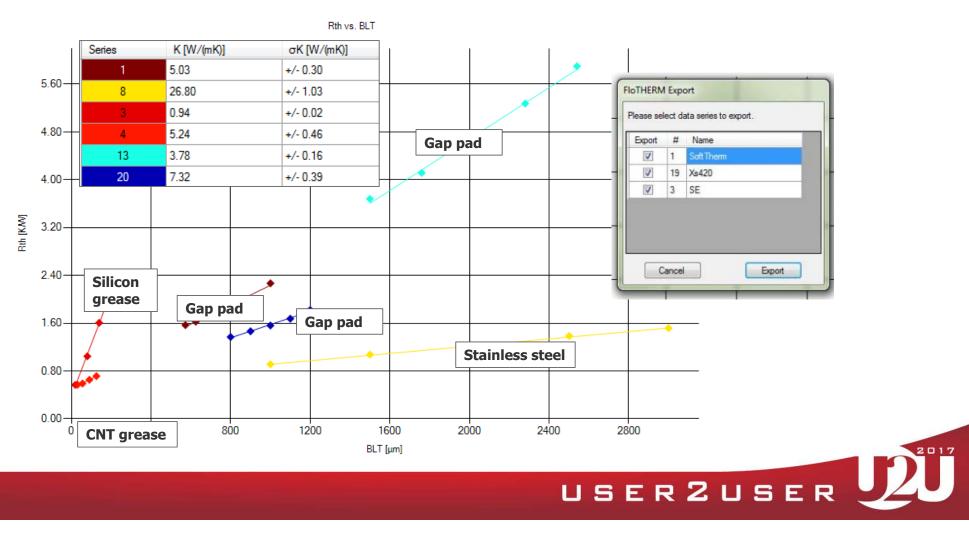
- Mechanics for thickness control
- Diode for heating and sensing
- Control electronics
- + T3Ster for other functions







### Similar measurements with similar UI



# 240A/11V Booster (PWB240A) Motivation: LS200 limitationa

- External power supply required for the operation below 40A
- Gate driver is grounded, not even multiple boosters can drive one IGBT half-bridge
- Lack of negative sensor current -> limited possibilities in MOSFET measurement
- Noise issues in some measurement setups
- Complicated manufacturing, and calibration



# **240A/11V Booster (PWB240A)**

 Built from the modules used also in the 1800/3600A power testers

### Specifications:

- Heaiting current: 1x10..240A/10V, not grounded
- Sensing current: 1x -1A..1A, grounded
- Gate driver: 4x -10..25V, not grounded
- 4U high main box + 2x1U power supply;
- Complete solution: 2x120A/12V power supplies included in the bundle

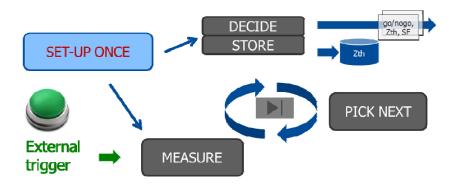
### Capabilities:

- Easy measurement of IGBT half-bridges both the gate drivers and the heating current sources are floating, not grounded
- Can heat MOSFET on open channel and measure on body diode
- Built-in R<sub>ds,on</sub> generator for one device (+ LV booster compatible rear connector for external VCB generator)



# **NEW PRODUCT ROADMAP**

# **Volume / Integrated testing – FY18**



- Same tests repeated (same- or similar part)
- Set-up once
- Test on external trigger
- Measurement results are stored for post processing
- Automated decision making (go / no-go, binning)

### **Status**

- First test system in PacRim / Japan
- Second test system is being built



# What is volume / integrated testing

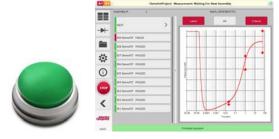
### **User interface**

- Touch UI / like PWT
- Workflow oriented
- Configuration aware
- Engineers and technicians



### **Automation**

- Repeated measurements
- Group testing
- "Pushbutton"
- Built in analysis



### Integration

- Works with other systems
- "Give us an API!"
- "Can we script?"
- (Not yet) going in- line

We have to control the measurement

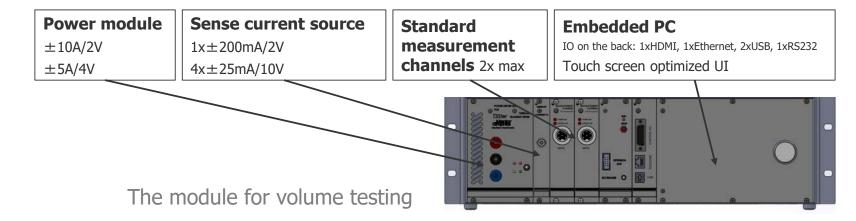
PC shall be included

Modular set-up for the measurement case

Do we have the modules?



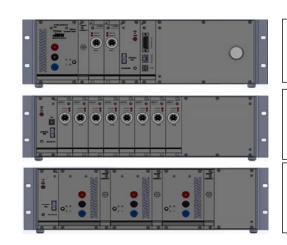
### T3Ster S



- T3Ster size subrack: a 2 ch T3ster, PC inside, touch-screen
- No transistor drive, booster can be added
- Single PN, a bit cheaper than T3Ster
- Touch UI for a subset of defined T3Ster measurements
- Can be integrated to other systems

### T3Ster IC

The module for IC testing



T3Ster S

#### **Sense Box**

Up to 8 additional measurement channels

#### Force box (1 or 2)

3 or 6 additional power and sensor current modules

- Builds on T3Ster-S: has 10 sense channels, 4-7 force channels
- Heating capability: 2V 10A (or 2A 10V)
- Multicore IC measurements (negative current)
- Transfer thermal resistance measurements



### **PWT600A Learnings**

### **Benefits**

- Throughput (16 DUTs)
- Smaller size (no coldplate)



### Issues

- From field specs (30V-s please)
- Increased to 48V (for 16 devices)
- 16 DUTs in serial
- 15kW PSUs (output capacitance)
- Focus on switching (not on auxiliary circuits)

### Could have had

- Connection in parallel (a bit higher costs)
- 16 DUTs = 4x4 DUTs
- Quicker development (= more testing time)
- Unified HW architecture (QA benefits, lead times)

Let's learn from it



### **PWT 600A 4x4C 12V**

- Same capacity (16 DUTs)
- 4 heating channels at 600A 12V, 4x4 measurement channels
- Built from the circuits of the 1800A
- No cold-plate or hydraulics, ~ 19 inch rack
- Offers most users the right specs or even slightly more
- Complementary offering to the 600A PWT



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